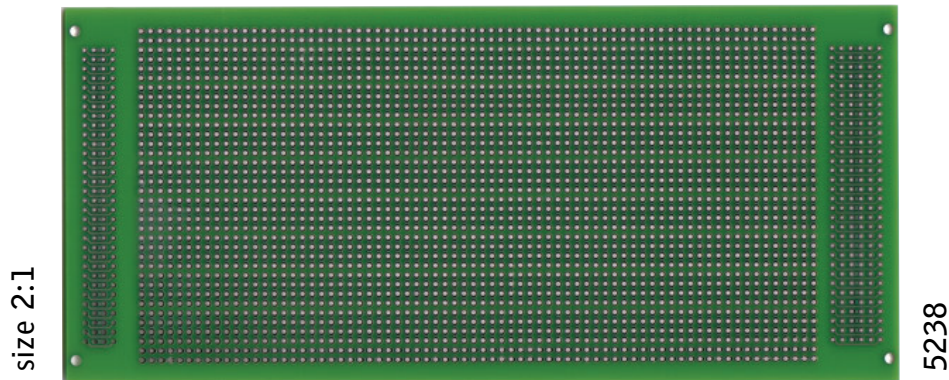


# Prototyping board KU-2



- Epoxy fibre-glass FR4 thickness 1,6 mm
- Double-sided copper thickness 35  $\mu$ m
- Hot Air Solder Levelling
- Hole diameter 1,0 mm
- Size 100 x 220 mm
- Connector 32/64/96 pin DIN41612 C
- Hole spacing 2,54 mm
- Plated through holes
- General hole mounted electronics